

Intel® 440MX Entry-level Communications Appliance Reference Design

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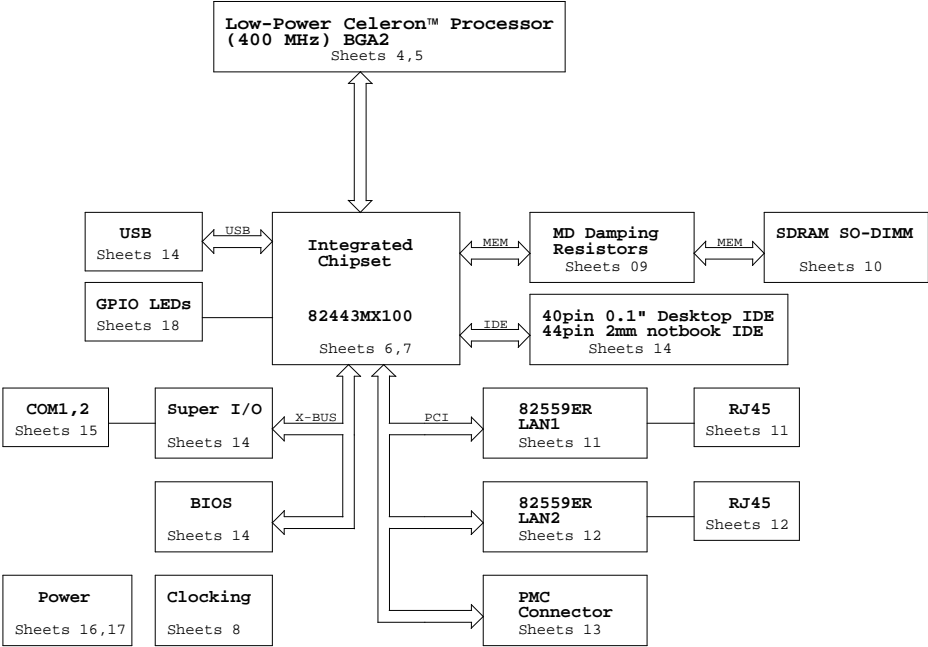
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Intel® 440MX Entry-level
Communications Appliance Reference Design

Block
Diagram



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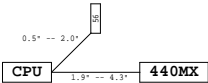
Intel Corporation 5000 W. Chandler Blvd. Chandler, AZ 85226		
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General Board Design Requirements

- >> PWB must be routed using six (6) layers, with the following stackup:
- Layer 1: Signal, VIP5, V2P5, and V5P0 Busses
 - Layer 2: Signal, No CPU/BX Traces
 - Layer 3: Split Power Plane -- V3P3 Plane, V2P0 Island
 - Layer 4: GND
 - Layer 5: Signal
 - Layer 6: Signal
- >> Right angle traces must not be used.
- >> Vias for decoupling capacitors must be kept as close as possible to the capacitor pad.
- >> Trace impedance must be 65 ohms, +/- 10%
- >> Total board thickness must be .062".
- >> Board material must be FR-4.
- >> GND layers must not be split.
- >> Top and bottom (outer) layers must be no less than 1/2 oz copper before plating, inner layers must be 1 oz copper.
- >> Series terminating resistors must be kept as close to the driving pin as possible.
- >> Daisy chain signals going to more than one point, do not use stubs.
- >> Unless otherwise noted, all signal traces must be between 5 and 6 mil width.
- >> Unless otherwise noted, minimum space between traces is 15 mils, including adjacent layers.
- >> Specific routing requirements are included throughout schematic sheets.
- >> One registration target must be included on each corner of the board.

CPU Routing Requirements

- >> Route all GTL traces between CPU and 440MX as shown in the diagram to the right.
- >> Route all traces between CPU and 440MX on a layer adjacent to a ground plane (preferably bottom layer), without layer changes.
- >> All traces between CPU and 440MX should differ in length by no more than 1000 mils.
- >> Minimum space between traces is 15 mils (unless otherwise noted), this includes adjacent signal layers.
- >> Minimum space between traces may be reduced to 5 mils when breaking out of a footprint. The total length of trace routed using 5 mil spacing must be less than 250 mils.
- >> The following signals require 25 mil spacing from other traces, including adjacent layers.
- HA#[3:3], HD#[63:0], BREQ0#, ADS#, BNR#, BPRI#, HLOCK#, DEFER#, HTRDY#, DBSY#, DRDY#, HIT#, HITM#, H_A2OM#, FLUSH#, H_IGNNE#, H_INIT#, H_INTR, H_NMI, PWR_OK_2P5, PX4_SMI#, SLP#, STPCLK#, 100/66#, PERR#, HRESET#, HREQ#[4:0], RS#[2:0], THERMD[P-N], CPU_GTL_REF[7:0], PLL[2:1], (TCK,TMS,TDI, TDO, TRST#, PRDY#, PREQ#).
- >> Route THRM DP and THRM DN close together as a pair (no more than 250 mil difference in length), on same layer, in parallel, and 25 mils min from any other trace.
- >> Route CPU_GTLREF using 25 mil minimum width trace, and separate from all other traces by 25 mils minimum.
- >> Route PLL[2:1] using 25 mil minimum width trace, minimize loop area, and separate from all other traces by 25 mils minimum.



Clock Specific Routing Requirements

- >> A clock trace must not alternate layers.
- >> A clock trace must be separated by a minimum of 25 mils from any other trace, including serpentine, 11 mils is OK when going between pins or balls.
- >> The CPU clock length must be between 1" and 9", and 460 mils shorter than the 440MX clock. The 440MX clock and all PCI clocks must be matched in length, except for the PMC clock which must be 2" shorter than all other PCI clocks.
- >> SDRAM_CLK[1:0] must be matched in length, and between 1" and 3" in length.
- >> CLKOUT, from the SDRAM clock driver to the 440MX, must be between 3.5" and 5.5" in length, and 2.5" longer than SDRAM_CLK[1:0].
- >> Trace length between BX-DCLK0 and SDRAM clock driver (signal REF) must be between 1" and 6".

IDE Specific Routing Requirements

- >> Place IDE connector within 3" of 440MX.
- >> Place IDE series terminating resistors within 500 mils of the 440MX.

Power Supply Specific Routing Requirements

- >> All unrelated signals and power planes must be kept away from the switching circuits.
- >> All traces associated with the input power/ground connectors, and the capacitors connected to these connectors, must be routed with minimum length and maximum width.
- >> See the Power Supply schematic sheet for complete restrictions.

Memory Bus Specific Routing Requirements

- >> Minimum trace width is 5 mils.
- >> Minimum space between traces is 10 mils, this includes adjacent signal layers.
- >> Minimum space between memory traces and other types of traces is 25 mils, this includes adjacent signal layers.
- >> Memory address, data, and control lines must be routed as separate groups and treated as different signal types.
- >> The MD, DQM, CS#, CKE, SRAS#, SCAS#, WE#, and MA signals (between BX and SODIMM) must be between 1" and 3" in length, matched to within 600 mils.

Memory Bus GROUPS -- SODIMM Names

- >> Address Signals: MAA[13:0]
- >> Data Signals: MD#[63:0]
- >> Control Signals:
- CKE[1:0], SMBDATA, SMBCLK, CSA[1:0]#, WE_A#, SCAS_A#, SRAS_A#

PCI Bus Specific Routing Requirements

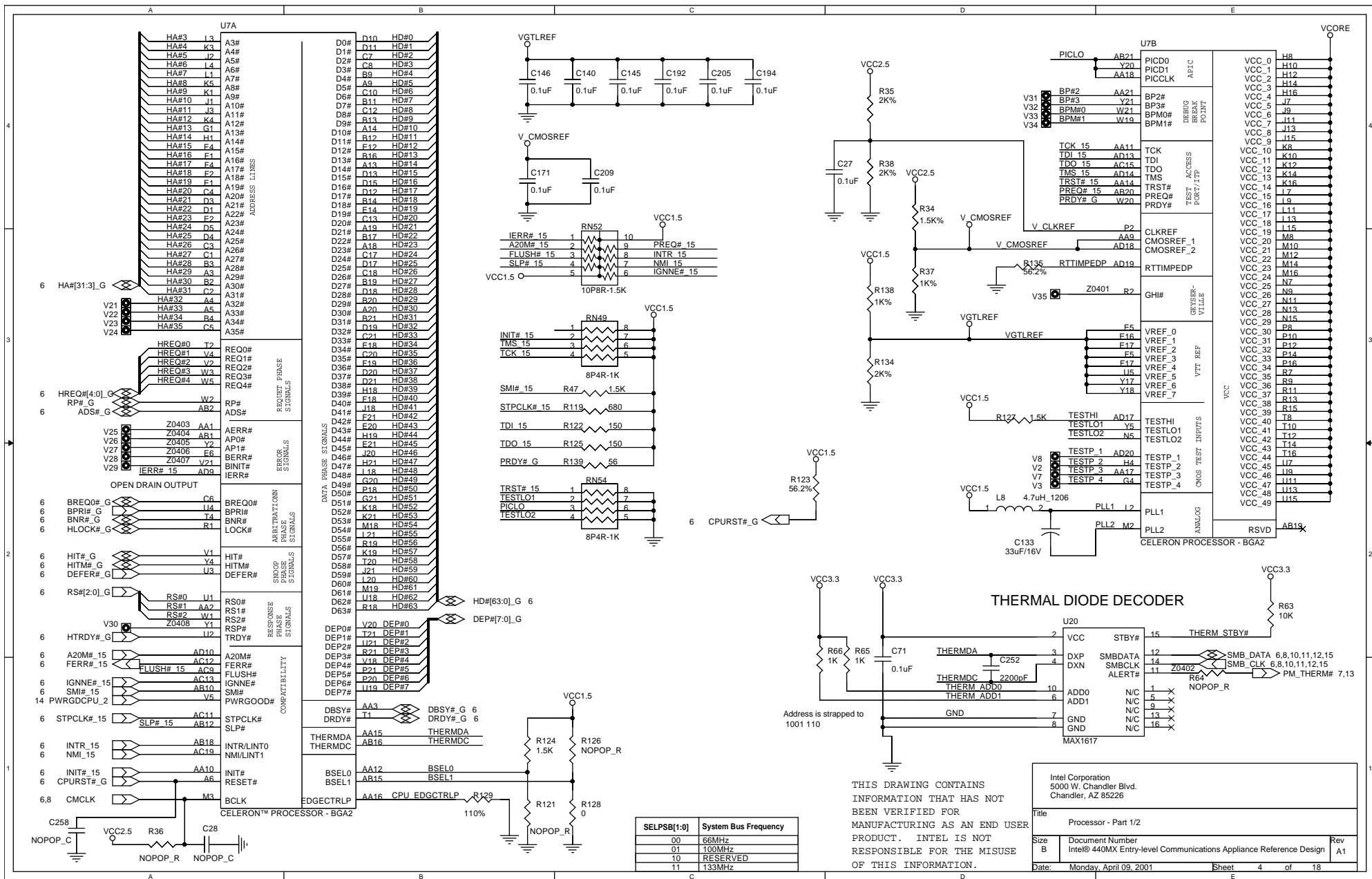
- >> The 440MX must be the last device on the PCI bus.
- >> PCI bus max length must be less than 6".

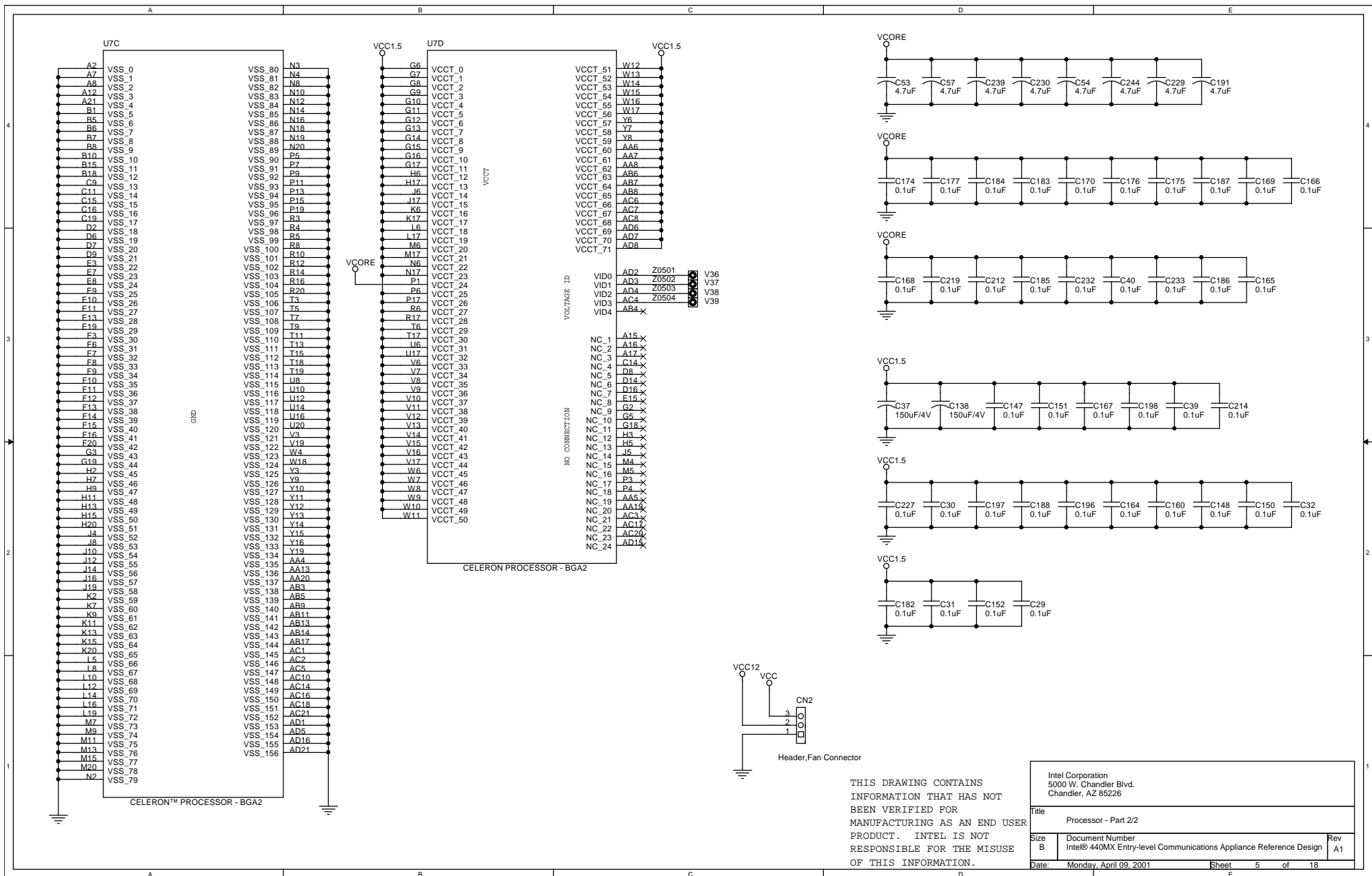
PCI Bus GROUPS

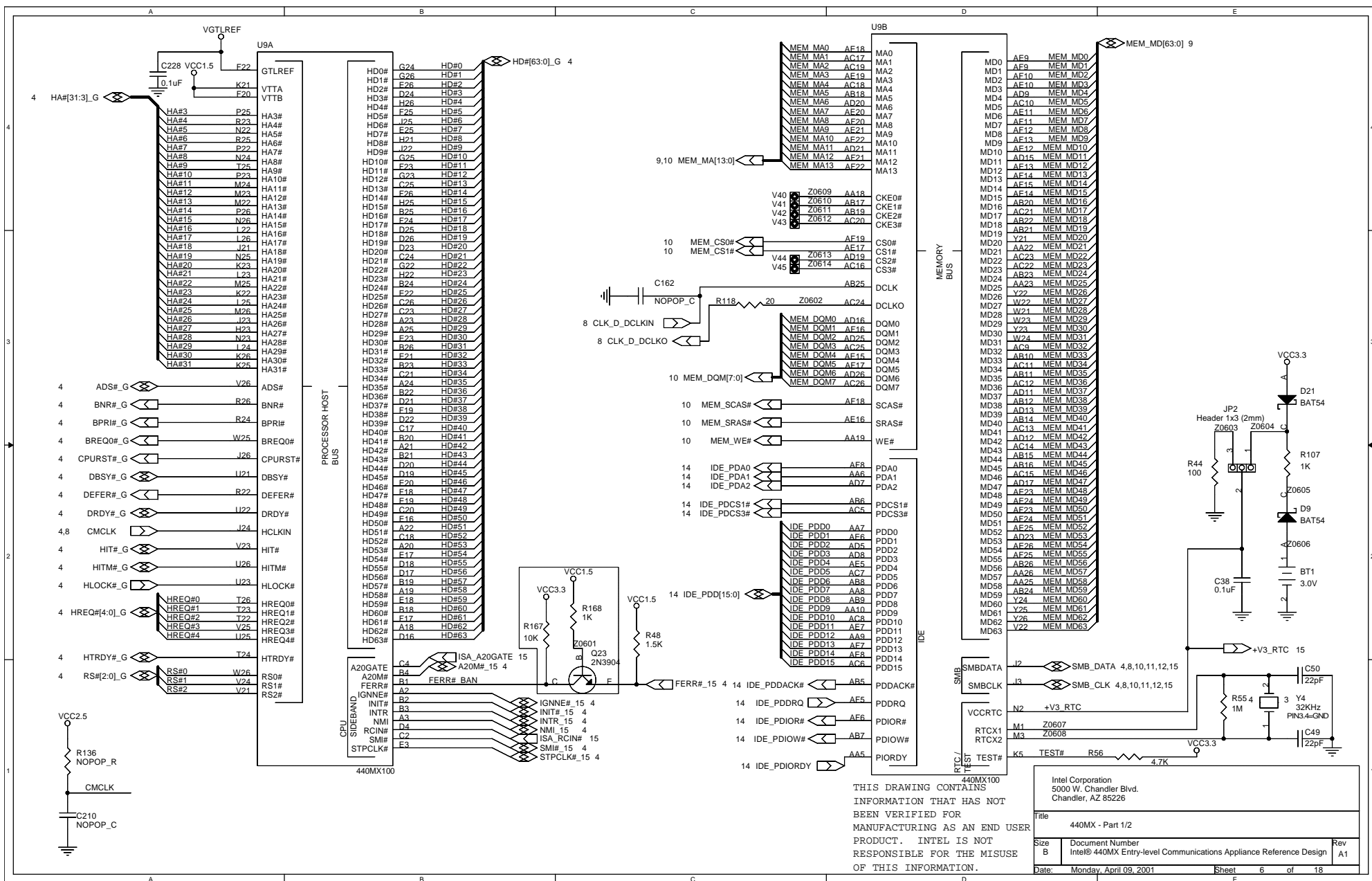
- >> Address/Data Signals: AD[31:0]
- >> Control Signals:
- BUSMD1#, C/BE[3:0]#, REQ1#, GNT1#, INT[A:D]#, PCIRST#, FRAME#, TRDY#, IRDY#, STOP#, DEVSEL#, SERR#, PERR#, PAR, LOCK#

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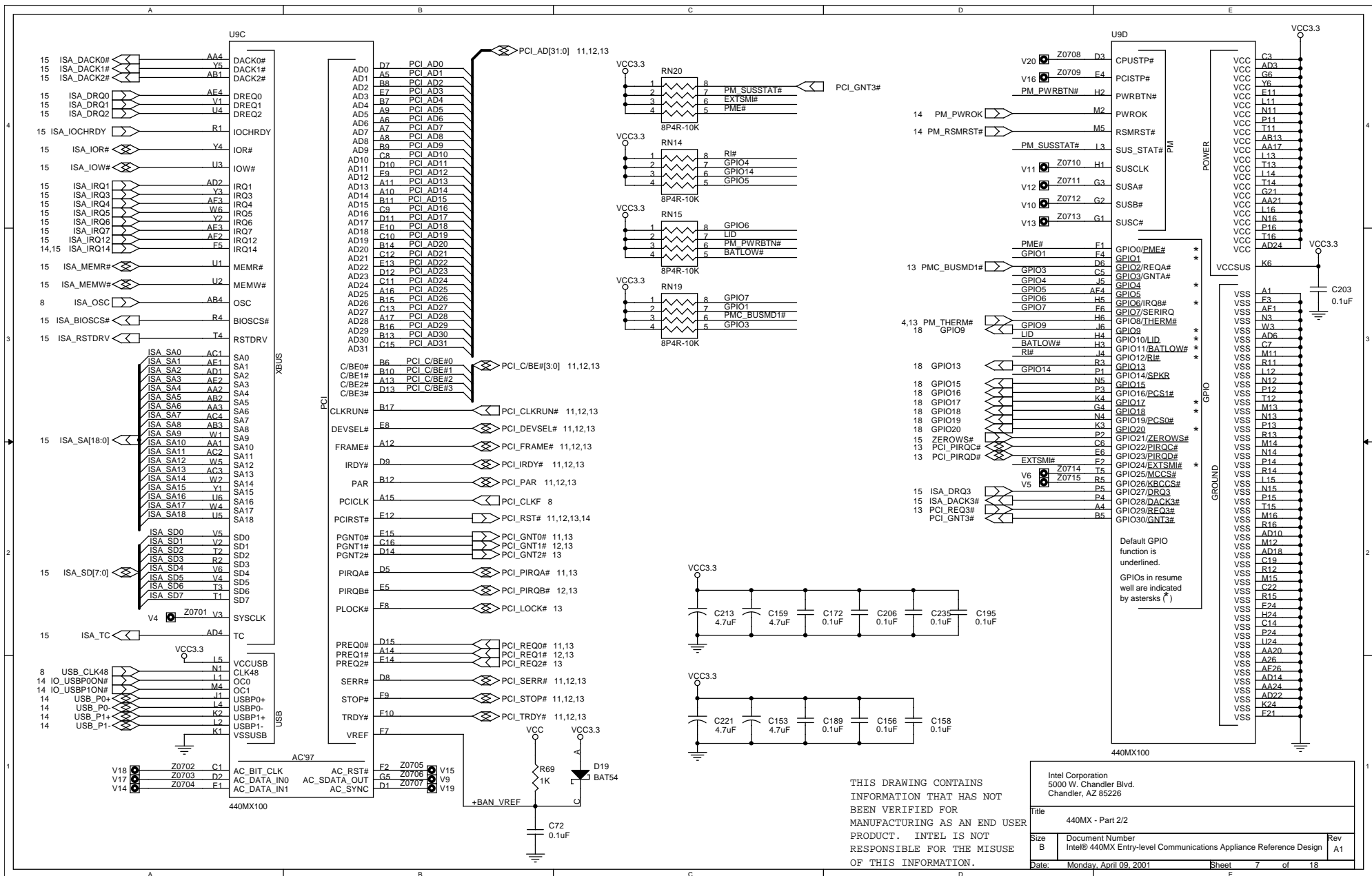
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Title		Routing Guidelines	
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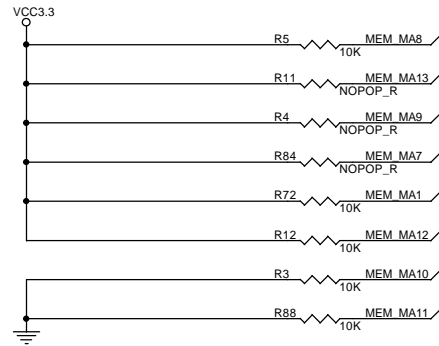


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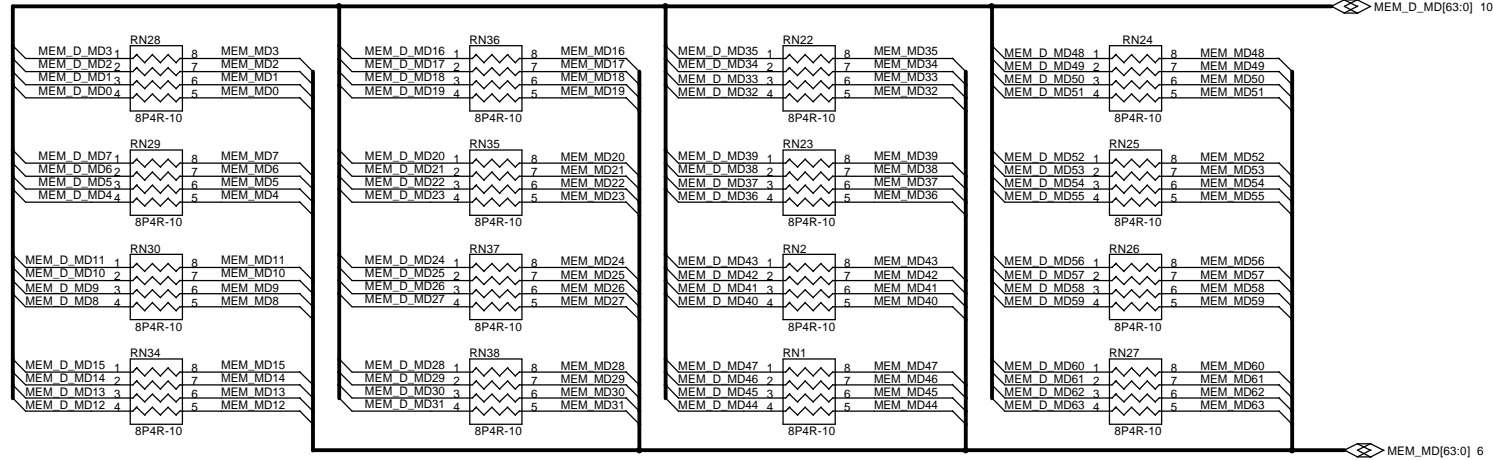


STRAPPING OPTIONS

BUS RATIO SETTINGS				
NMI (MA13)	INTR (MA9)	IGNNE# (MA7)	A20M# (MA1)	CPU Frequency
Lo	Lo	Hi	Lo	300MHz (3/1)
Lo	Hi	Hi	Lo	350MHz (7/2)
Lo	Lo	Lo	Hi	400MHz (4/2)
Lo	Hi	Lo	Hi	450MHz (9/2)
Lo	Lo	Hi	Hi	500MHz (5/1)
Lo	Hi	Hi	Hi	550MHz (11/2)
Hi	Lo	Lo	Lo	600MHz (6/1)
Hi	Hi	Lo	Lo	650MHz (13/2)
Hi	Lo	Hi	Lo	700MHz (7/1)
Hi	Hi	Hi	Lo	750MHz (15/2)
Hi	Lo	Lo	Hi	800MHz (8/1)

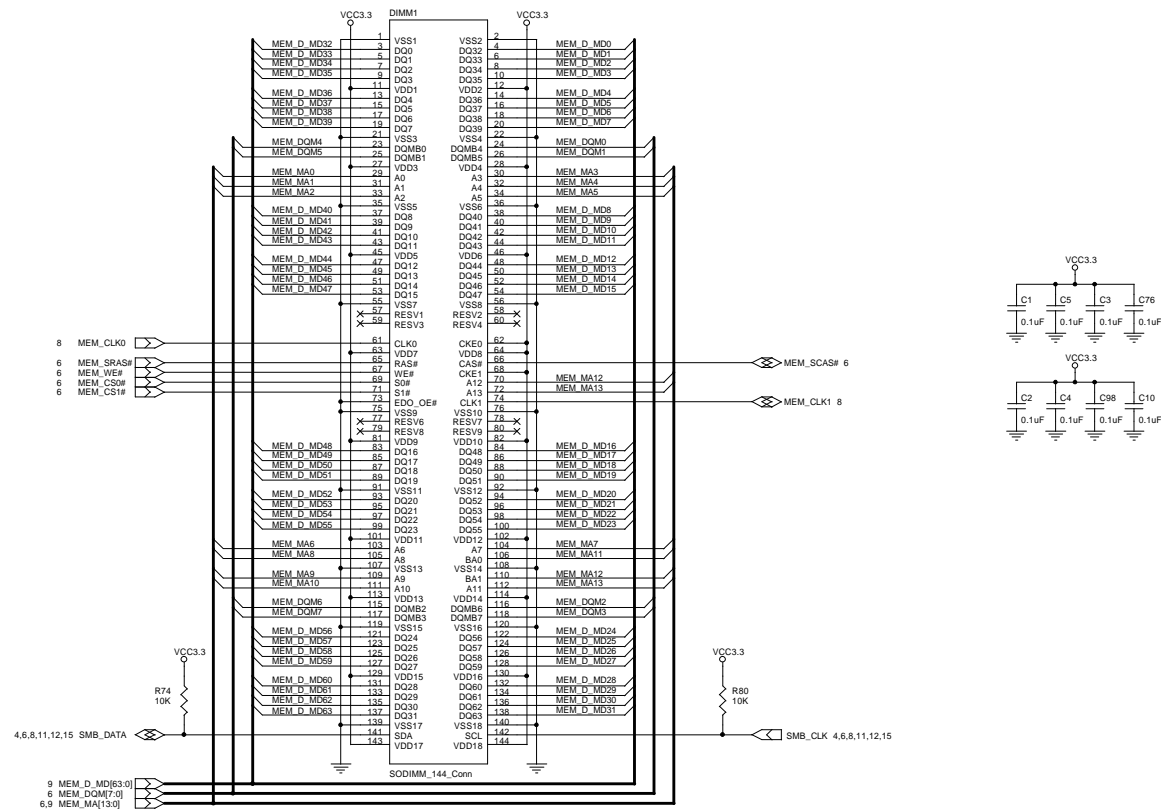


LINE	FUNCTION	PULL-UP	PULL-DOWN	440MX100 DEFAULT
* MA8	High Frequency VCO	High Speed	Normal Speed	Pull down
MA13	CPU Clock Ratio (NMI)	Not used		Pull down
MA9	CPU Clock Ratio (INTR)			Pull down
MA7	CPU Clock Ratio (IGNNE#)			Pull down
MA1	CPU Clock Ratio (A20M#)			Pull down
MA12	Host Frequency Select	100MHz	66MHz	Pull down
* MA10	Quick Start Select	Quick Start		Pull up
* MA11	Pipelined Operation	Pipelined	Non-pipelined	Pull up



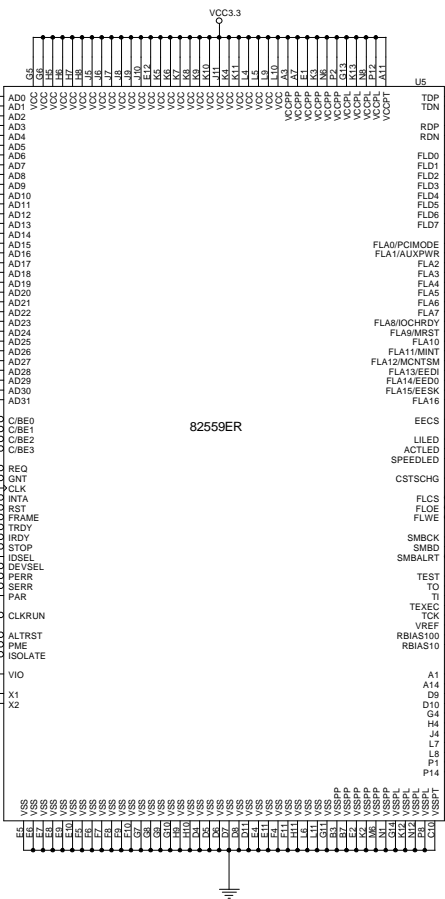
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Title Memory Data Bus Damping Resistors			
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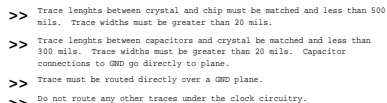


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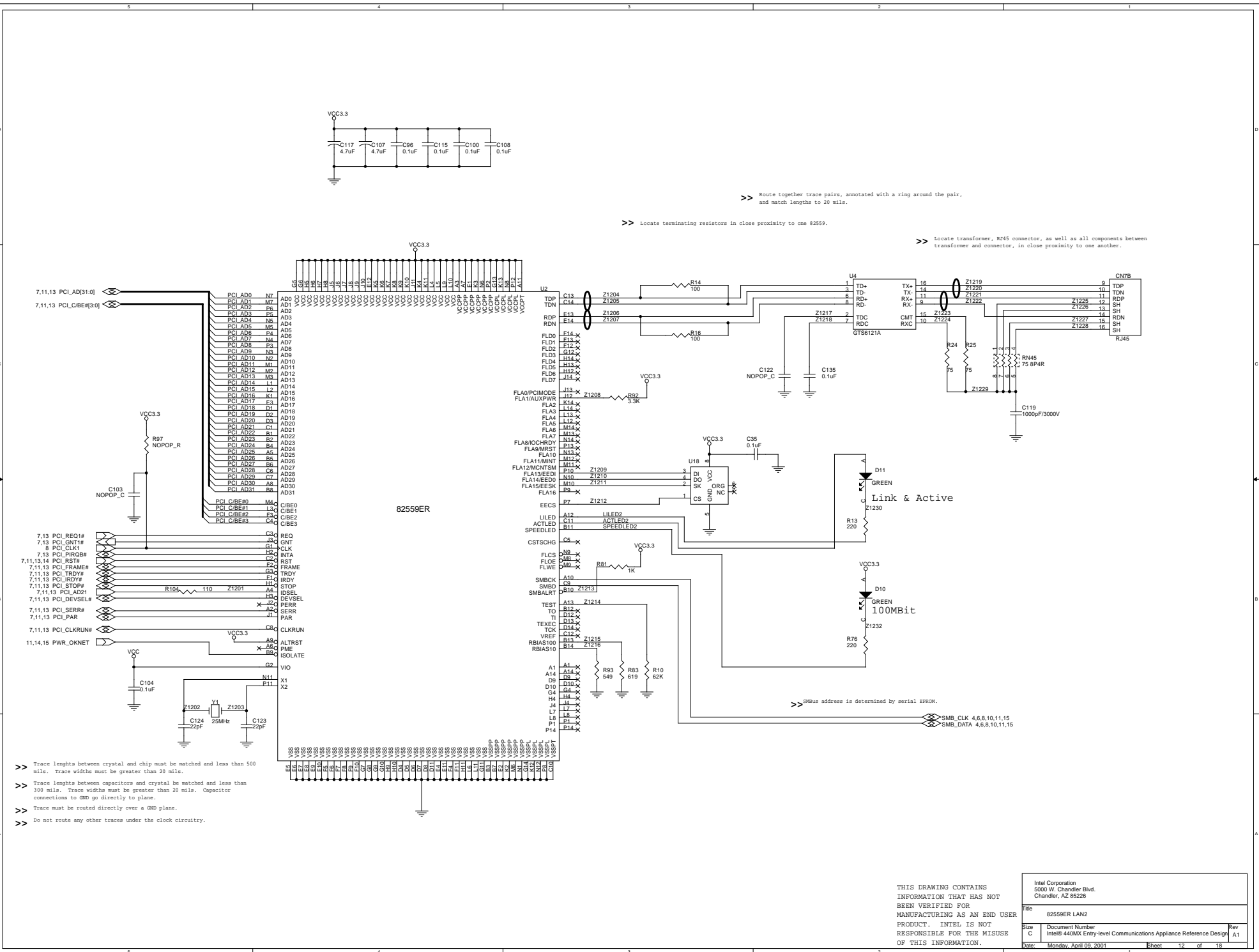


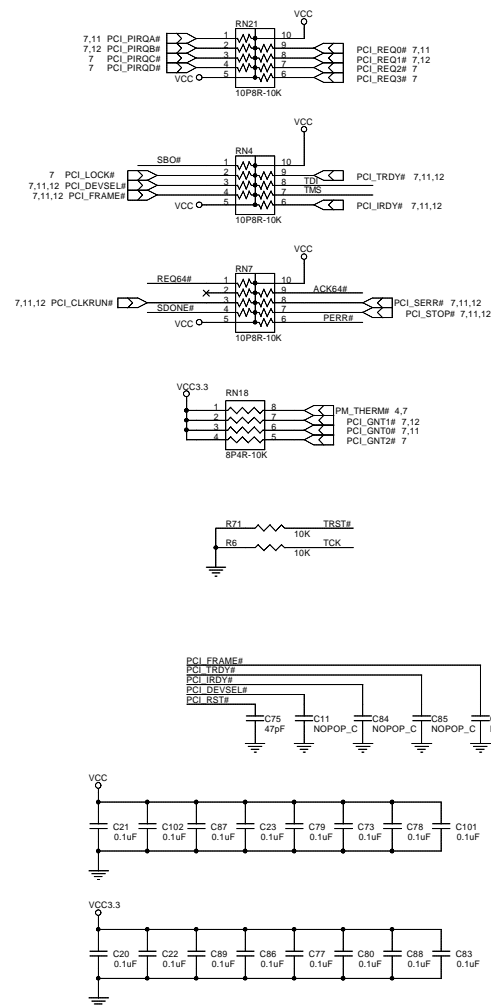
>> Locate transformer, RJ45 connector, as well as all components between transformer and connector, in close proximity to one another.



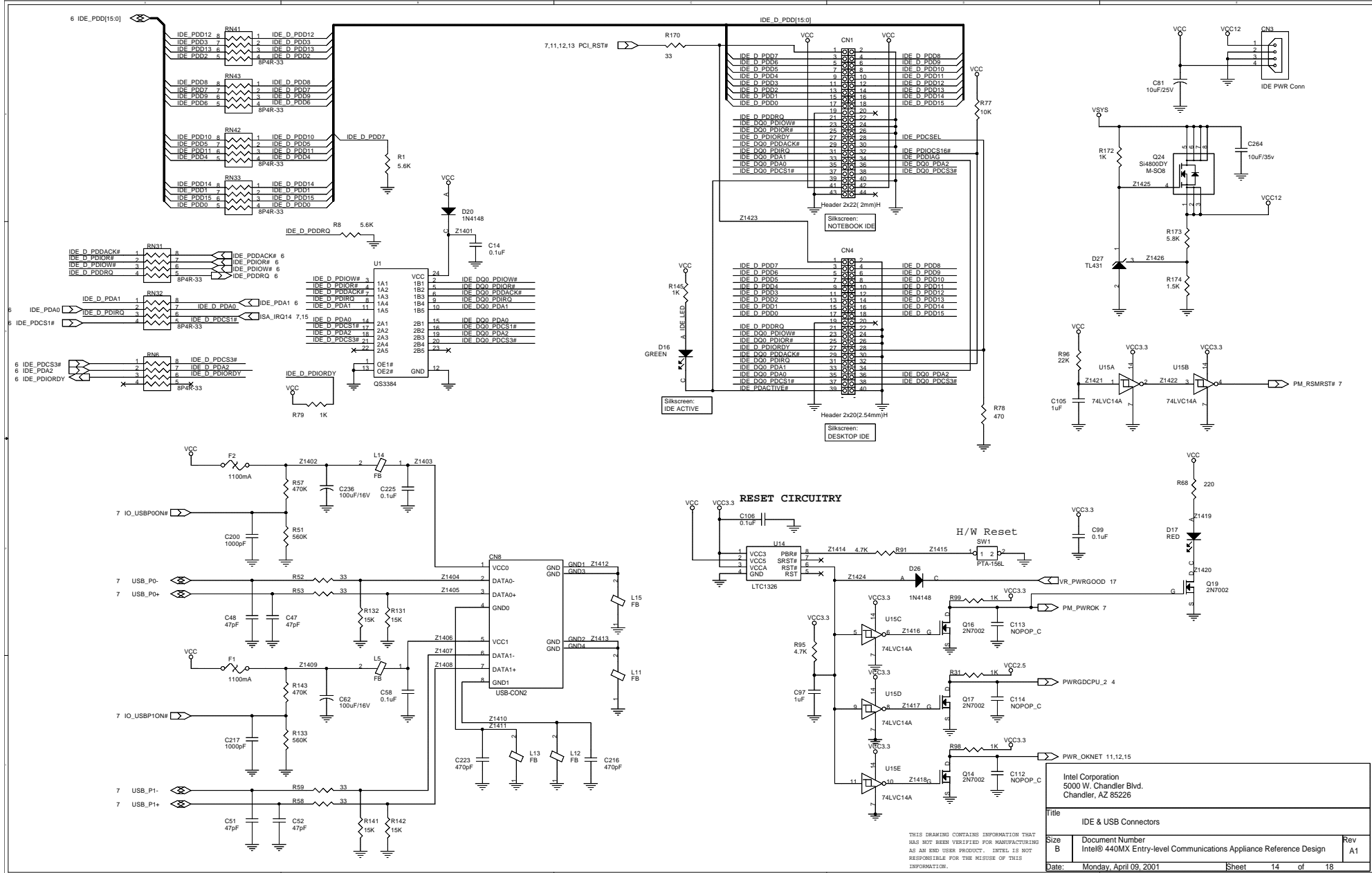
SMB_CLK 4,6,8,10,12,15
SMB_DATA 4,6,8,10,12,15

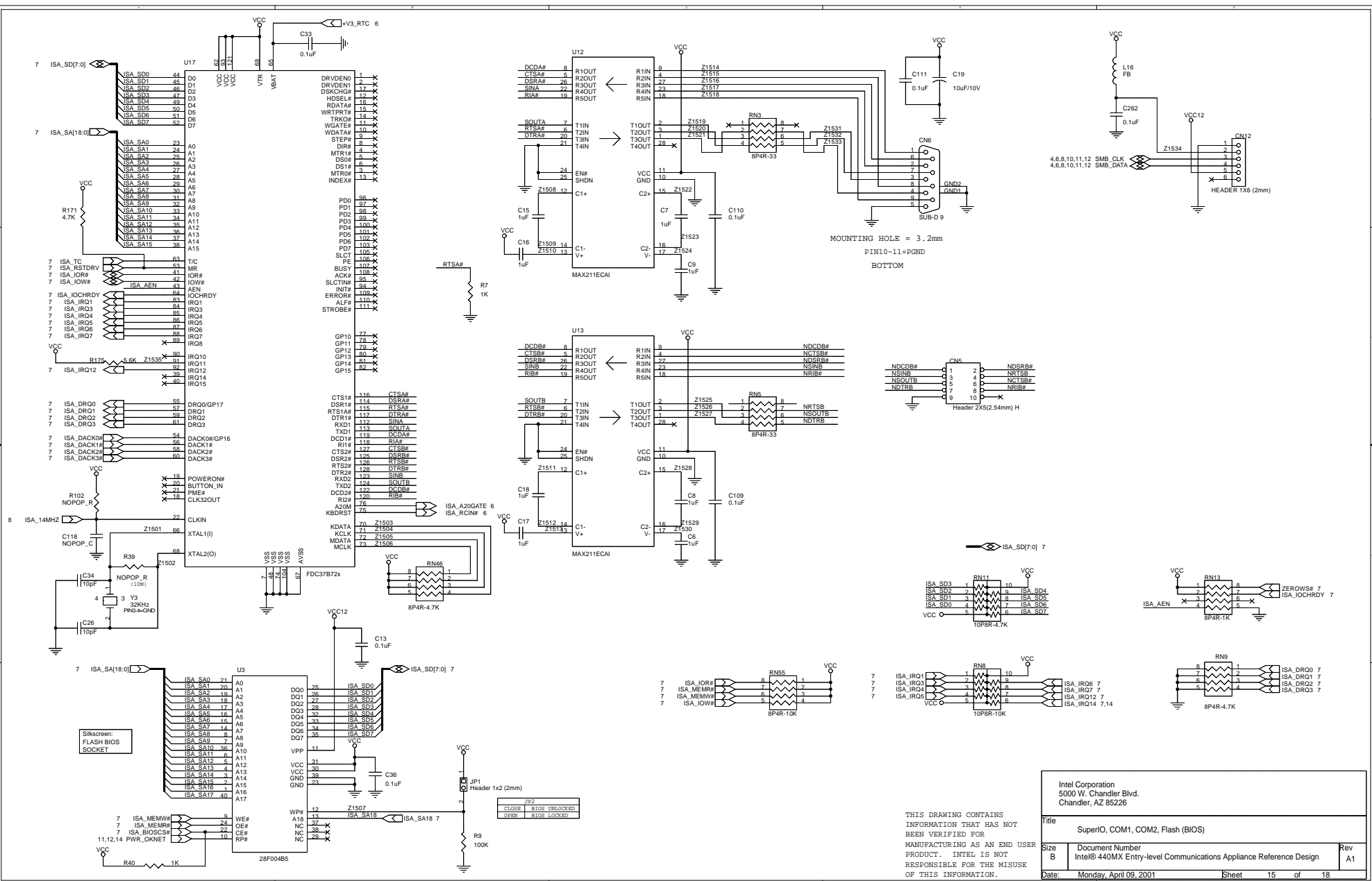
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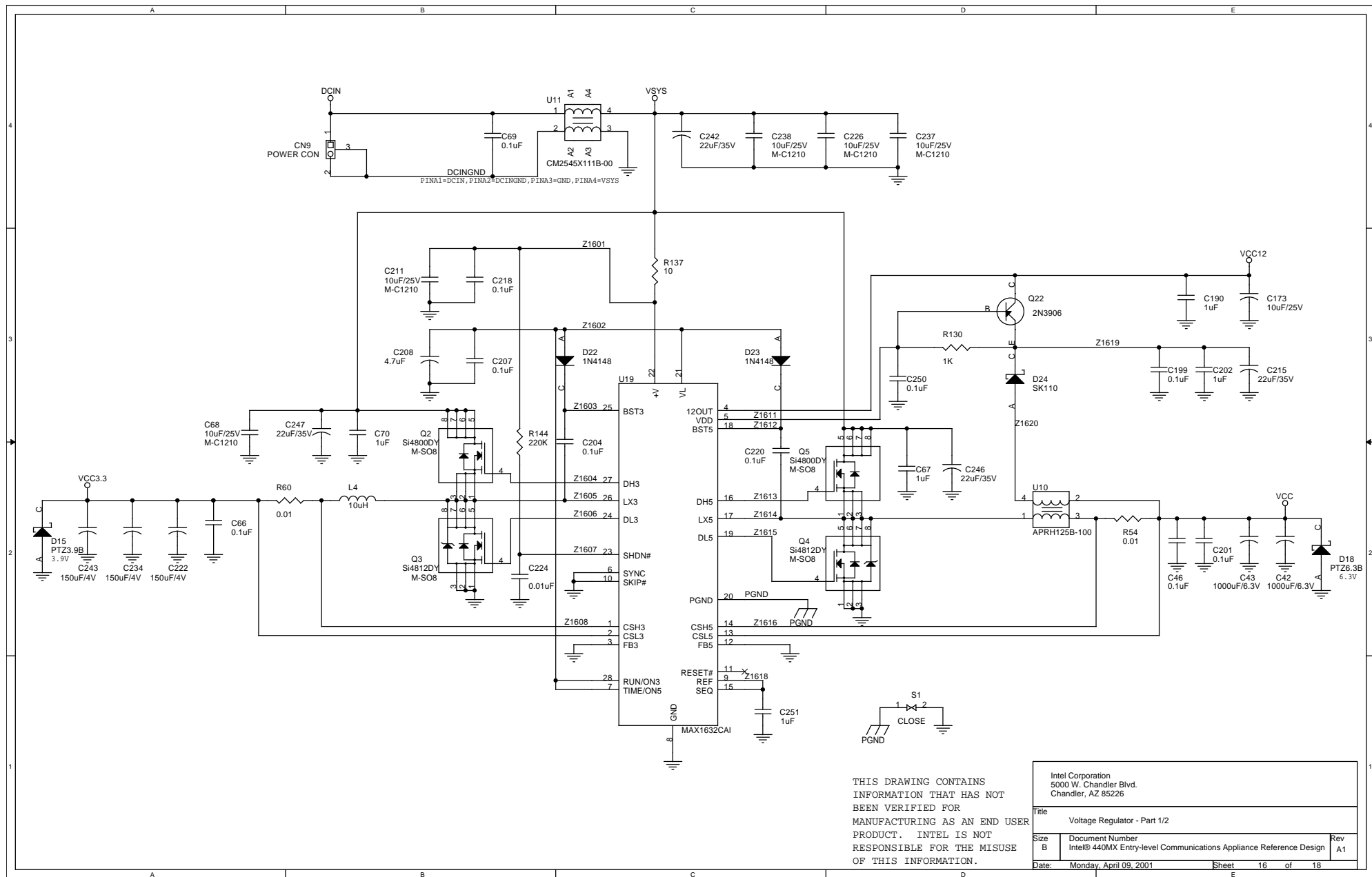
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Title	SuperIO, COM1, COM2, Flash (BIOS)
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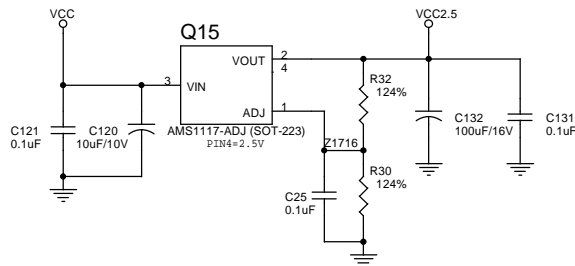
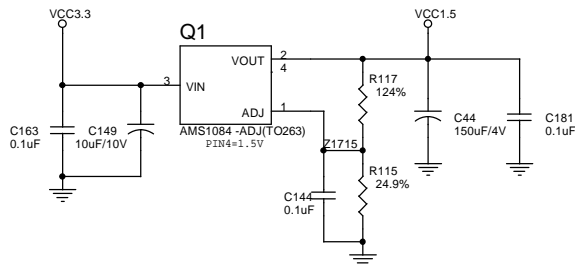
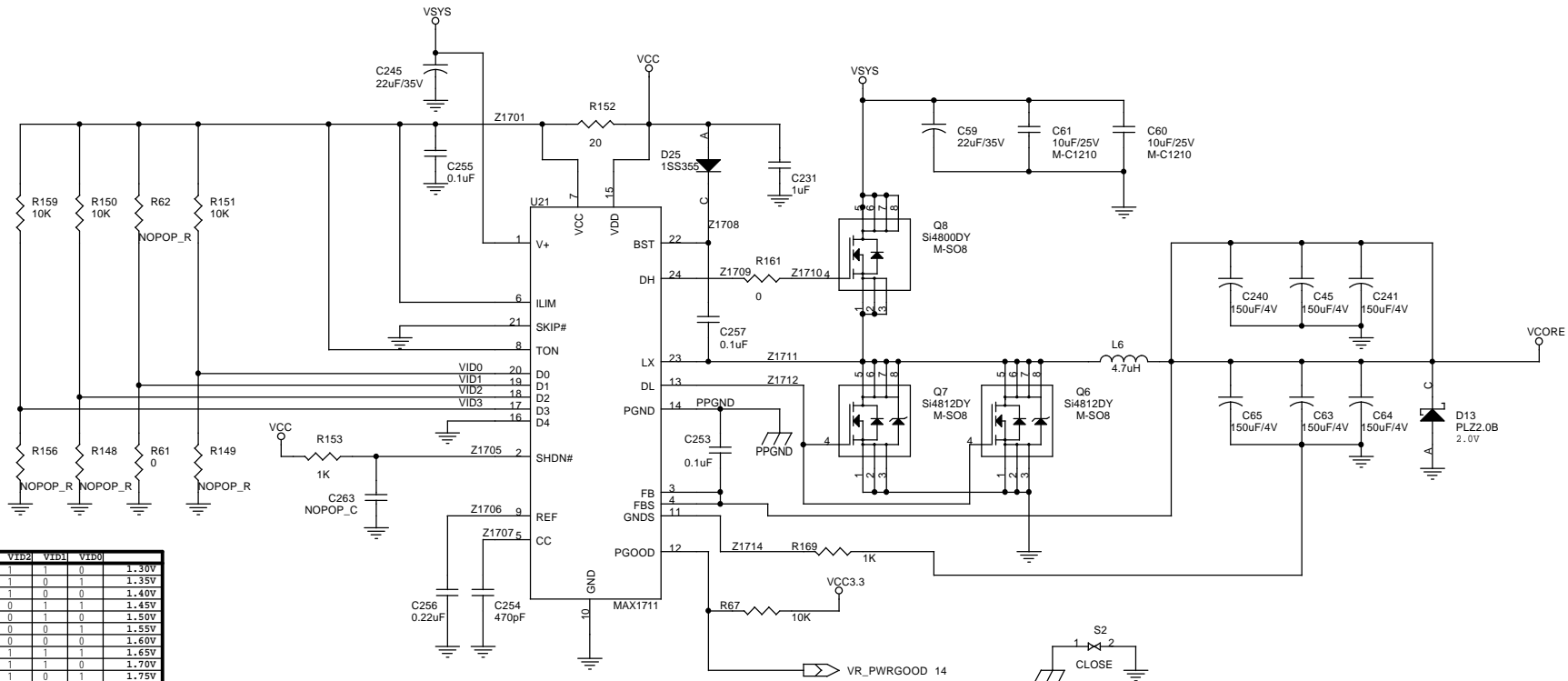
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VID3	VID2	VID1	VID0	
1	1	1	0	1.30V
1	1	0	1	1.35V
1	1	0	0	1.40V
1	0	1	1	1.45V
1	0	1	0	1.50V
1	0	0	1	1.55V
1	0	0	0	1.60V
0	1	1	1	1.65V
0	1	1	0	1.70V
0	1	0	1	1.75V
0	1	0	0	1.80V
0	0	1	1	1.85V
0	0	1	0	1.90V
0	0	0	1	1.95V
0	0	0	0	2.00V



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